

Special Issue

Metal Forming

Message from the Guest Editor

This Special Issue will present the latest works in research related to several aspects of the metal forming processes, from microstructure formation to simulation and industrial applications. We are inviting papers that include but are not limited to any of the following thematic areas:

- Metal Forming problems;
- Structure and properties evolution during plastic deformation;
- Mathematical Modeling and Simulation of metals forming;
- Structure formation during metals forming processes;
- Superplasticity and superplastic forming;
- Shape memory effect.

Keywords

- metal forming
- plastic deformation
- metallic alloys
- microstructure
- mechanical properties
- stress-strain data
- deformation behavior
- modeling
- simulation
- superplasticity
- shape memory effect

Guest Editor

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Deadline for manuscript submissions

closed (20 March 2022)



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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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